## Innovative Chemical Solutions for MEMS and Microelectronics

### SU-8

**Product Line**
- SU-8
- SU-8 2000
- SU-8 3000

**Material Attributes**
- i-line imaging
- High aspect ratio with vertical sidewalls
- Photo-definable ultra-thick structures
- Outstanding chemical and thermal stability
- Excellent dry-etch resistance
- 0.5 - > 200 µm film thickness

**Applications**
- MEMS
- Microfluidics
- Optoelectronics
- Displays

### KMPR

**Product Line**
- KMPR 1000

**Material Attributes**
- i-line imaging
- TMAH development
- Temporary or permanent
- High chemical and plasma stability
- High dry-etch resistance
- Good adhesion to metals

**Applications**
- MEMS
- DRIE etch mask
- Plating

### Perminex™

**Product Line**
- PermiNex™ 1000
- PermiNex™ 2000

**Material Attributes**
- Negative tone, photoimageable resists
- Low temperature processing (< 200°C)
- High quality, void-free bonding
- Excellent adhesion to silicon and glass

**Applications**
- Fabrication and capping of microstructures
- MEMS, MOEMS, microfluidic devices

### LOR/PMGI

**Product Line**
- PMGI SF
- LOR A
- LOR B

**Material Attributes**
- Won’t intermix when over-coated with most top imaging resists
- Single step development of bi-layer stack in TMAH or KOH developers
- Quick and clean removal in conventional resist strippers
- High resolution metallization (< 0.25 µm)
- Very thick metallization (> 4 µm)

**Applications**
- Data storage
- III-V semiconductors
- Optoelectronics
- MEMS

### PMMA

**Product Line**
- PMMA 950
- PMMA 495
- Co-Polymers

**Material Attributes**
- E-Beam and X-ray imageable
- High resolution
- Wide range of firm thickness
- Excellent adhesion to most substrates
- Excellent dry-etch resistance

**Applications**
- Direct write e-beam lithography
- T-gates
- PHEMT
- Metallization

### Ancillary Products
- Developers, removers, edge bead removers
- Photoresist thinners
- Adhesion promoters

### Custom Manufacturing
- Dilutions, dye addition
- PAG adjustments, solvent mixtures
- Or your custom application